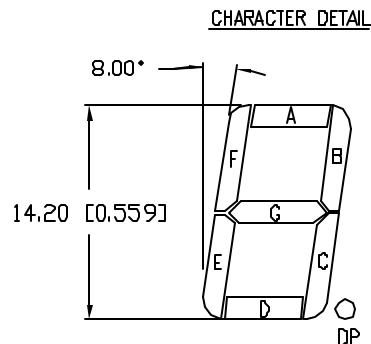
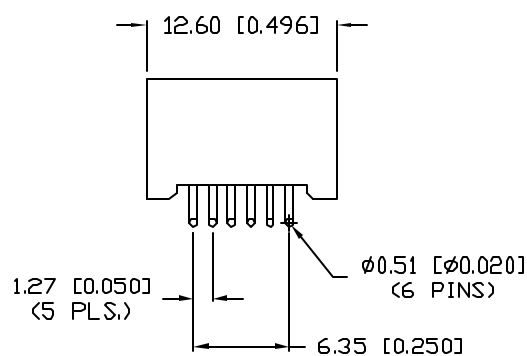
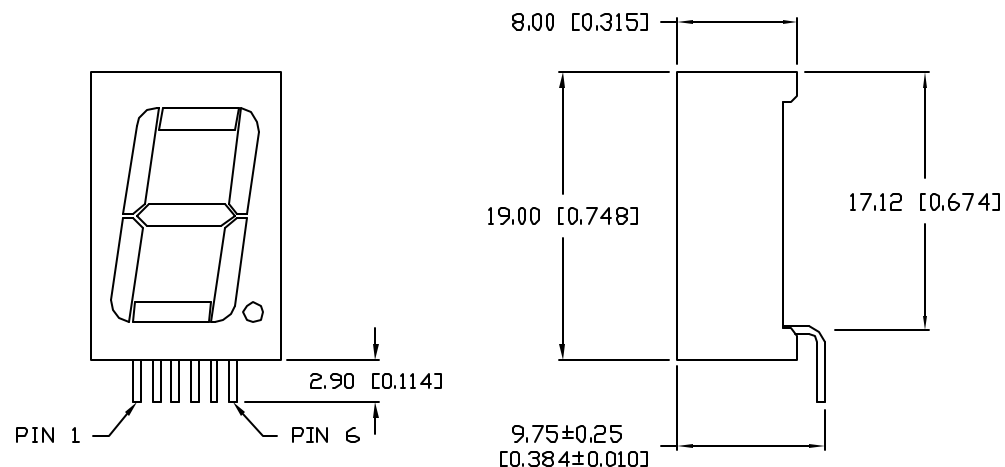


UNCONTROLLED DOCUMENT

PART NUMBER
LDS-M513RI-RAREV.
B

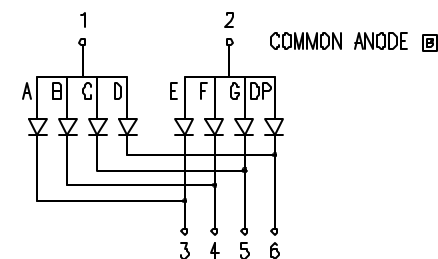
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10BRDR. & REDRAWN.	7-13-99
B	E.C.N. #10574.	12-20-99

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=10\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		585 (YELLOW)		nm	
FORWARD VOLTAGE		2.1	2.5	V _f	
REVERSE VOLTAGE	5.0			V _r	I _r =100μA
AXIAL INTENSITY		2250		μcd	I _f =10mA
EMITTED COLOR:	YELLOW				
FACE COLOR:	GRAY				
SEGMENT COLOR:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C PER CHIP

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C
SOLDERING TEMP.	+260	°C
2.0mm FROM BODY	3 SEC. MAX	

* $t < 10\mu\text{s}$ 

UNCONTROLLED DOCUMENT

*UNLESS OTHERWISE SPECIFIED TOLERANCE IS $\pm 0.25\text{mm}$ ($\pm 0.010"$)REV.
BPART NUMBER
LDS-M513RI-RA

CONFIDENTIAL INFORMATION
THE INFORMATION CONTAINED IN THIS DOCUMENT IS THE PROPERTY OF LUMEX INC. EXCEPT AS SPECIFICALLY AUTHORIZED IN WRITING BY LUMEX INC., THE HOLDER OF THIS DOCUMENT SHALL KEEP ALL INFORMATION CONTAINED HEREIN CONFIDENTIAL AND SHALL PROTECT SAME IN WHOLE OR IN PART FROM DISCLOSURE AND DISSEMINATION TO ALL THIRD PARTIES.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

LUMEX
INCORPORATED

290 E. HELLEN ROAD
PALATINE, ILLINOIS 60067
PHONE: 1-847-359-2790
WEB: HTTP://WWW.LUMEX.COM

0.56" SEVEN SEGMENT SINGLE DIGIT DISPLAY,
585nm YELLOW CHIPS, GRAY FACE WITH WHITE SEGMENTS,
COMMON ANODE, RIGHT DECIMAL POINT.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE: 11-13-95
			PAGE: 1 OF 1
			SCALE: N/A

TM/BC